



WS488 Paste Flux



Paste Flux

Features:

- Excellent Wetting
- Wide Process Window
- Aqueous Wash with Water

Description:

AIM WS488 Paste Flux is a water washable tacky/rework flux designed to wet virtually all solderable electronic surfaces, components, assemblies, and substrates. AIM WS488 Paste Flux may be used for general touch up or rework of printed circuit boards, and for attaching spheres to ball grid array (BGA) packages. WS488 Paste Flux offers excellent wetting activity whether reflowed by hand, hot-air rework stations, convection reflow ovens, or vapor phase soldering systems. WS488 Paste Flux is compatible with all tin-lead and lead-free alloys and can be used for a wide range of applications. WS488 Paste Flux can be brushed, dispensed, pin transferred, or stencil printed. WS488 Paste Flux is available in 10 cc and 30cc syringes.

Flux Application:

When being used in rework, application should be limited to the area being worked. Application via dispense needle, brush or a cotton swab is recommended.

Cleaning:

WS488 Paste Flux can be cleaned easily with normal tap water. Deionized water is recommended for the final rinse. A temperature of 38°C – 60°C (100°F - 140°F) is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but not required.

Handling and Storage:

- WS488 paste flux has a refrigerated shelf life of 1 year 4°C (39°F) or 6 months at room temperature.
- Allow the paste flux to warm naturally to ambient temperature (2 hrs.) prior to use.
- Do not store new and used paste in the same container.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Material Safety Data Sheet** for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Physical Properties:

Parameter	Value
J-STD-004	ORM1
Acid Number	53.89 mg KOH per gram flux

Parameter	Value
Viscosity	Gel-like consistency
Appearance	Amber-light yellow

Corrosion Testing:

Parameter	Requirements	Results
Copper Mirror (24 hrs @ 25°C, 50%RH)	IPC-TM-650-2.3.32	Medium
Halide Test (Silver Chromate)	IPC-TM-650-2.2.33	Halides Present

Surface Insulation Resistance:

Reference	Property	Pass-Fail Criteria	Results
IPC-TM-650 method 2.6.3.3 85°C / 85% R.H.	Control coupons	>1E+9 Ω at 96 and 168 hrs	Pass
	Sample coupons – pattern up	>1E+8 Ω at 96 and 168 hrs	Pass
	Sample coupons – pattern down	>1E+8 Ω at 96 and 168 hrs	Pass
	Post-test visual inspection	No dendrite growth or corrosion	Pass

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AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

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